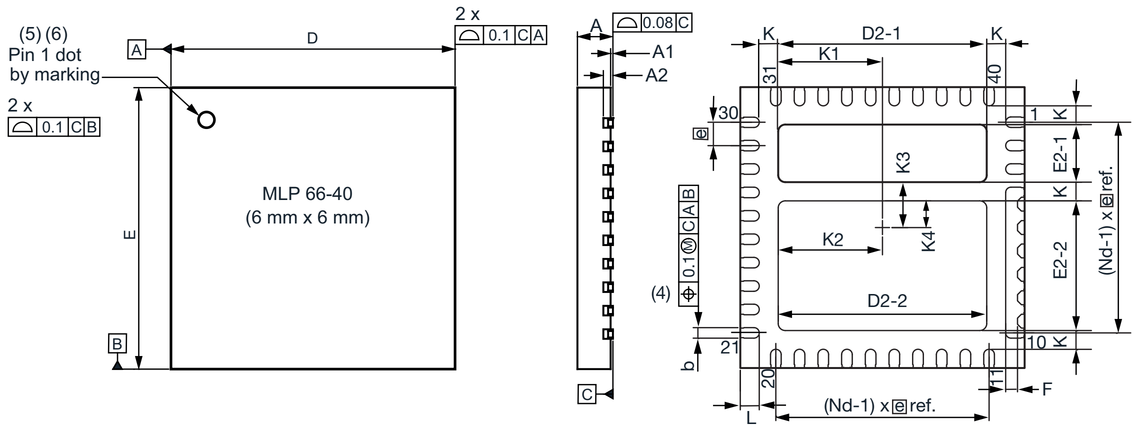
PowerPAK® MLP66-40 BWL Case Outline for SiC32201



Top view

Side view

Bottom view

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A (8)	0.70	0.75	0.80	0.028	0.030	0.032
A1	0.00	-	0.05	0.000	-	0.002
A2	0.20 ref.			0.008 ref.		
b (4)	0.20	0.25	0.30	0.078	0.098	0.011
D	5.90	6.00	6.10	0.232	0.236	0.240
e	0.50 BSC			0.019 BSC		
F	0.20	0.25	0.30	0.008	0.010	0.012
E	5.90	6.00	6.10	0.232	0.236	0.240
L	0.35	0.40	0.45	0.013	0.015	0.017
N (3)	40			40		
Nd (3)	10			10		
Ne (3)	10			10		
D2-1	4.30	4.40	4.50	0.169	0.173	0.177
D2-2	4.30	4.40	4.50	0.169	0.173	0.177
E2-1	1.13	1.23	1.33	0.044	0.048	0.052
E2-2	2.67	2.77	2.87	0.105	0.109	0.113
K	0.40 ref.			0.016 ref.		
K1	2.20 ref.			0.087 ref.		
K2	2.20 ref.			0.087 ref.		
K3	0.97 ref.			0.038 ref.		
K4	0.57 ref.			0.022 ref.		
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Notes

(1) Use millimeters as the primary measurement
(2) Dimensioning and tolerances conform to ASME Y14.5M. - 1994
(3) N is the number of terminals. Nd is the number of terminals in X-direction and Ne is the number of terminals in Y-direction
(4) Dimension b applies to plated terminal and is measured between 0.20 mm and 0.25 mm from terminal tip
(5) The pin #1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
(6) Exact shape and size of this feature is optional
(7) Package warpage max. 0.08 mm
(8) Applied only for terminals

For technical questions, contact: powerictechsupport@vishay.com